

L Number	Hits	Search Text	DB	Time stamp
2	1	4845041.PN. AND METAL	USPAT; US-PGPUB	2002/10/07 14:55
3	0	4845041.PN. AND METALLIC	USPAT; US-PGPUB	2002/10/07 14:55
4	1	4845041.PN. AND SUBSTRATE	USPAT; US-PGPUB	2002/10/07 14:55
5	1	4845041.PN. AND SAMPLE	USPAT; US-PGPUB	2002/10/07 14:55
1	1	4845041.PN.	USPAT; US-PGPUB	2002/10/07 15:08
6	3	4845041.URPN.	USPAT	2002/10/07 14:59
7	1660	204/192.3?.ccls.	USPAT	2002/10/07 15:13
8	1117	204/298.3?.ccls.	USPAT	2002/10/07 15:10
9	2355	204/192.3?.ccls. or 204/298.3?.ccls.	USPAT	2002/10/07 15:28
10	65	(204/192.3?.ccls. or 204/298.3?.ccls.) and (fusion or combustion)	USPAT	2002/10/07 15:10
11	293	204/192.3?.ccls.	EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:13
12	399	204/298.3?.ccls.	EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:13
13	675	204/192.3?.ccls. 204/298.3?.ccls.	EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:13
14	2	(204/192.3?.ccls. 204/298.3?.ccls.) and (fusion or combustion)	EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:15
15	3030	(204/192.3?.ccls. or 204/298.3?.ccls.) (204/192.3?.ccls. 204/298.3?.ccls.)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:15
16	282	((204/192.3?.ccls. or 204/298.3?.ccls.) (204/192.3?.ccls. 204/298.3?.ccls.)) and ((metal metallic) near2 (substrate article sample wafer))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:19
17	236	204/192.\$ccls.	US-PGPUB	2002/10/07 15:17
18	4	204/192.\$ccls. and (fusion)	US-PGPUB	2002/10/07 15:17
19	334	yasuhara-h\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:17

20	7	yasuhara-h\$.in. and (sputte\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB DERWENT	2002/10/07 15:17
21	1	2002-084365.NRAN.		2002/10/07 15:18
22	204	((((204/192.3?.ccls. or 204/298.3?.ccls.) (204/192.3?.ccls. 204/298.3?.ccls.)) and ((metal metallic) near2 (substrate article sample wafer))) and (heat\$3 cool\$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:22
23	15	"4624214"	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:21
24	0	((((204/192.3?.ccls. or 204/298.3?.ccls.) (204/192.3?.ccls. 204/298.3?.ccls.)) and ((metal metallic) near2 (substrate article sample wafer))) and (heat\$3 cool\$3)) and "4624214"	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:21
25	5	((((204/192.3?.ccls. or 204/298.3?.ccls.) (204/192.3?.ccls. 204/298.3?.ccls.)) and ((metal metallic) near2 (substrate article sample wafer))) and (heat\$3 cool\$3)) and anodes!	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:22
26	14	((((204/192.3?.ccls. or 204/298.3?.ccls.) (204/192.3?.ccls. 204/298.3?.ccls.)) and ((metal metallic) near2 (substrate article sample wafer))) and (heat\$3 cool\$3)) and cathodes!	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:22
27	17	((((204/192.3?.ccls. or 204/298.3?.ccls.) (204/192.3?.ccls. 204/298.3?.ccls.)) and ((metal metallic) near2 (substrate article sample wafer))) and (heat\$3 cool\$3)) and anodes!) (((((204/192.3?.ccls. or 204/298.3?.ccls.) (204/192.3?.ccls. 204/298.3?.ccls.)) and ((metal metallic) near2 (substrate article sample wafer))) and (heat\$3 cool\$3)) and cathodes!)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:24
28	2	4624214.pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:24
29	0	4624214.pn. and anode	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:24
30	0	4624214.pn. and cathode	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:24
31	833	(204/192.3?.ccls. or 204/298.3?.ccls.) and (cool\$4)	USPAT	2002/10/07 15:28

32	49	((204/192.3?.ccls. or 204/298.3?.ccls.) and (cool\$4)) and anodes!	USPAT	2002/10/07 15:28
33	86	((204/192.3?.ccls. or 204/298.3?.ccls.) and (cool\$4)) and cathodes!	USPAT	2002/10/07 15:28
34	29	((((204/192.3?.ccls. or 204/298.3?.ccls.) and (cool\$4)) and anodes!) and (((204/192.3?.ccls. or 204/298.3?.ccls.) and (cool\$4)) and cathodes!)	USPAT	2002/10/07 15:30
35	19786	sputte\$4 with etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:31
36	1	(sputte\$4 with etch\$4) and (fusion adj analy\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:31
37	7	(sputte\$4 with etch\$4) and (combustion adj analy\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:31
38	7	((sputte\$4 with etch\$4) and (fusion adj analy\$4)) ((sputte\$4 with etch\$4) and (combustion adj analy\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:32
39	188	(sputte\$4 with etch\$4) with ((metal or metallic) near2 (substrate article wafer sample))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:38
40	58	(sputte\$4 with etch\$4) with ((metal or metallic) near1 (substrate article wafer sample))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/07 15:39